

OL-NX5P1000

WLCSP12: wafer level chip-scale package; 12 bumps

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	29-3-2013

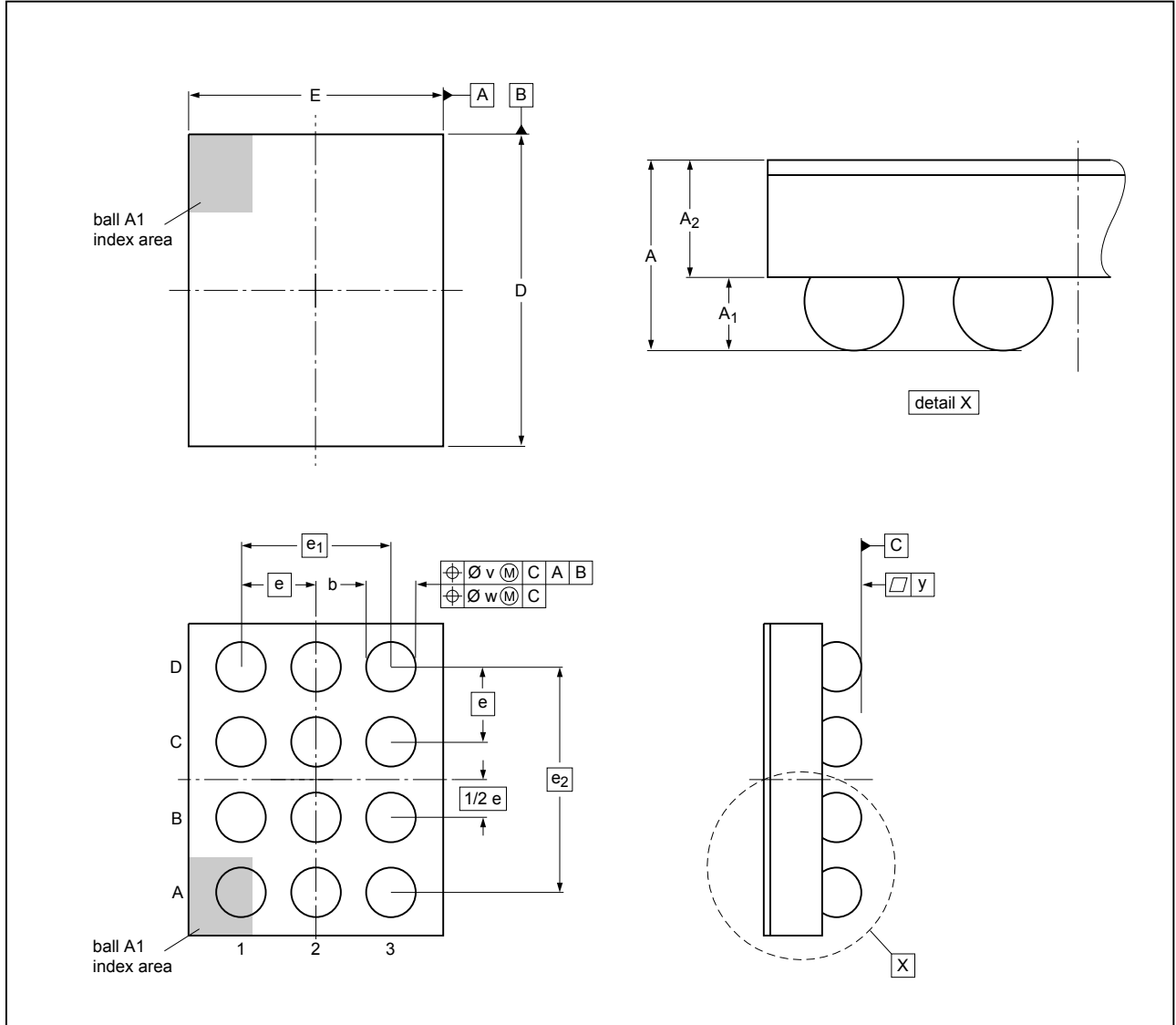
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.63	-	1.66	1.69	mm
E	package width	1.33	-	1.36	1.39	mm
A	seated height	0.47	-	0.51	0.55	mm
A ₂	package height	0.29	-	0.31	0.34	mm
e	nominal pitch	-	-	0.4	-	m
n ₂	actual quantity of termination	-	-	12	-	



2. Package outline

WLCSP12: wafer level chip-scale package; 12 bumps; 1.36 x 1.66 x 0.51 mm, 0.4 mm pitch (Backside coating included) NX5P1000E
NX5P3001/NX18P3001



0 2 mm scale

Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y
max	0.55	0.23	0.34	0.29	1.69	1.39						
nom	0.51	0.20	0.31	0.26	1.66	1.36	0.4	0.8	1.2	0.05	0.15	0.03
min	0.47	0.17	0.29	0.23	1.63	1.33						

wlcspl2_136-166-51_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
NX5P1000E NX5P3001/NX18P3001					-13-03-27- 13-03-29

Fig. 1. Package outline WLCSP (OL-NX5P1000)

3. Legal information

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Date of release: 8 February 2016
